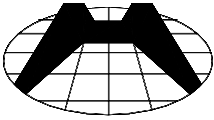
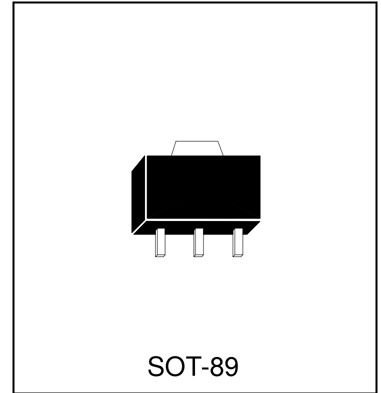


HI-SINCERITY
MICROELECTRONICS CORP.

HM965

NPN EPITAXIAL PLANAR TRANSISTOR



Description

The HM965 is designed for use as AF output amplifier and glash unit.

Features

- Low $V_{CE(sat)}$
- High performance at low supply voltage

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature .... -55 ~ +150 °C
  Junction Temperature .... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (T_A=25°C) .... 1.2 W
- Maximum Voltages and Currents (T_A=25°C)
  BV_{CBO} Collector to Base Voltage .... 40 V
  BV_{CEO} Collector to Emitter Voltage .... 20 V
  BV_{EBO} Emitter to Base Voltage .... 7 V
  I_C Collector Current (Continuous) .... 5 A
  I_C Collector Current (Peak PT=10mS) .... 8 A

Electrical Characteristics (T_A=25°C)

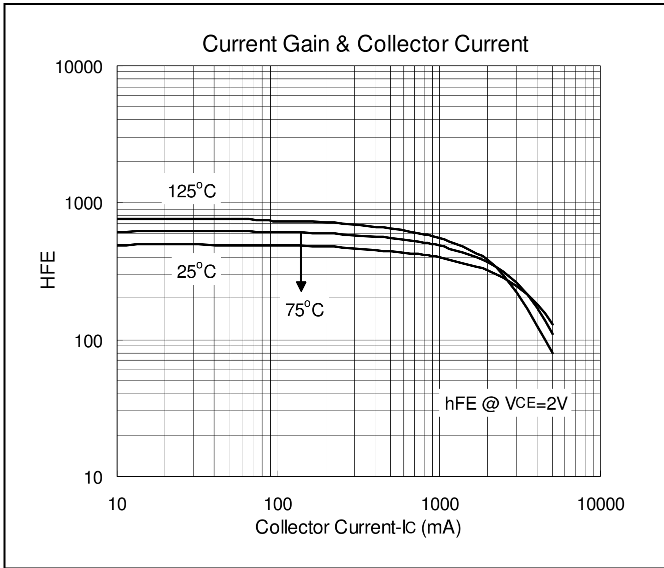
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	40	-	-	V	I_C=100uA
BV_{CEO}	20	-	-	V	I_C=1mA
BV_{EBO}	7	-	-	V	I_E=10uA
I_{CBO}	-	-	0.1	uA	V_{CB}=10V
I_{EBO}	-	-	0.1	uA	V_{EB}=7V
*$V_{CE(sat)}$	-	0.35	1	V	I_C=3A, I_B=0.1A
*h_{FE1}	340	-	800		V_{CE}=2V, I_C=0.5A
*h_{FE2}	150	-	-		V_{CE}=2V, I_C=2A
f_T	-	150	-	MHz	V_{CE}=6V, I_E=50mA
Cob	-	-	50	pF	V_{CB}=20V, f=1MHz

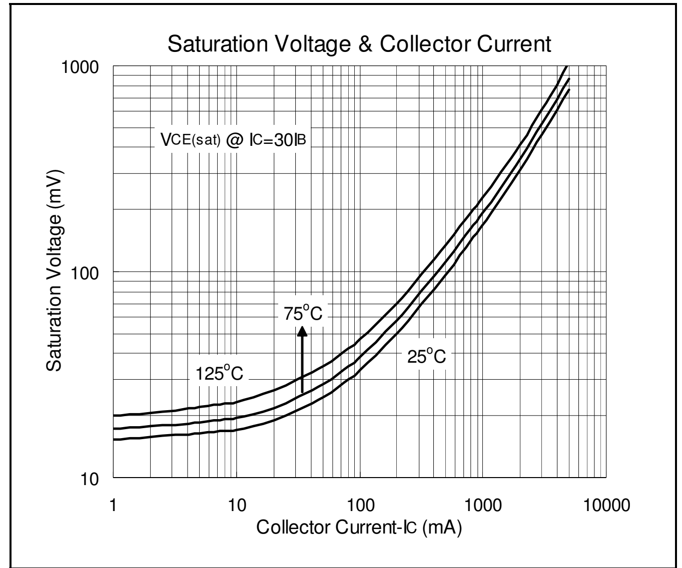
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

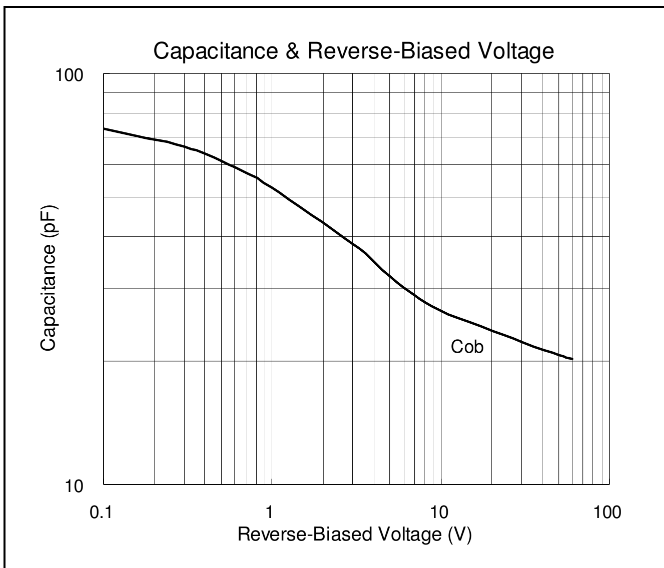
Classifications Of hFE1

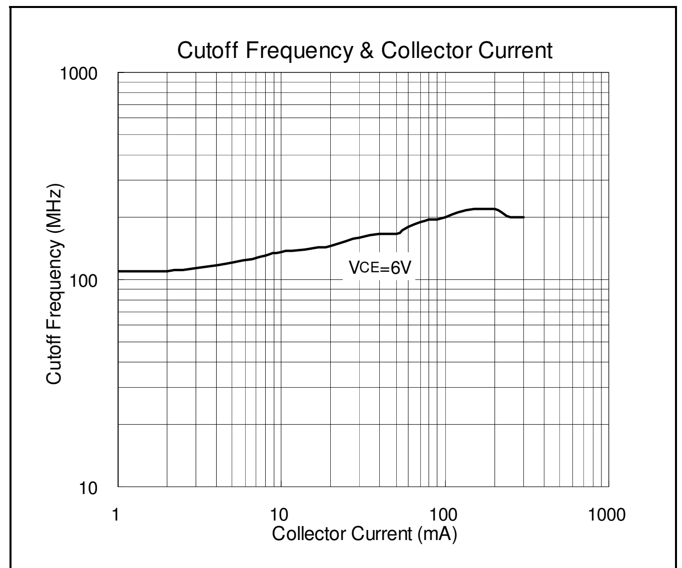
Rank	R	S
Range	340-600	560-800

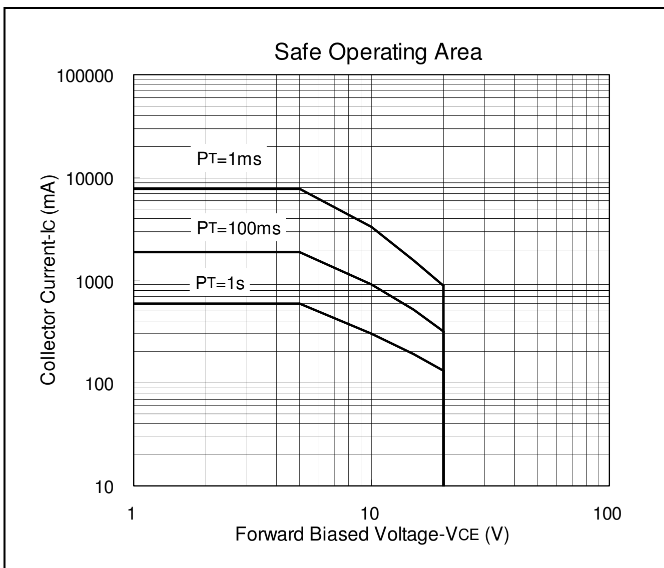
Characteristics Curve

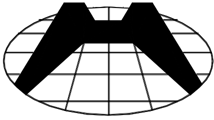












HI-SINCERITY
MICROELECTRONICS CORP.

SOT-89 Dimension

3-Lead SOT-89 Plastic
Surface Mounted Package
HSMC Package Code: M

Marking:

Date Code — Control Code
H 9 6 5
Pb Free Mark
Pb-Free: "•" (Note)
Normal: None

Note: Green label is used for pb-free packing

Pin Style: 1.Base 2.Collector 3.Emitter

Material:
- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	4.40	4.60
B	4.05	4.25
C	1.50	1.70
D	2.40	2.60
E	0.36	0.51
F	*1.50	-
G	*3.00	-
H	1.40	1.60
I	0.35	0.41

*: Typical, Unit: mm

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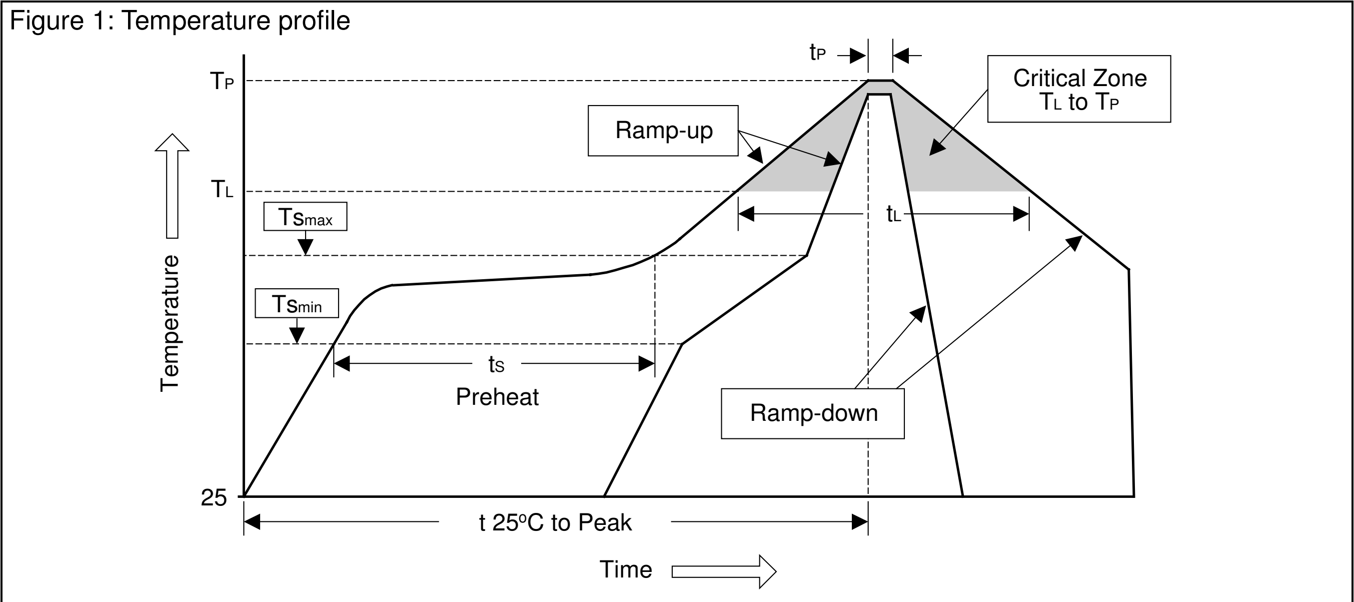
  Tel: 886-3-5983621~5 Fax: 886-3-5982931

Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%

2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (min to max) (ts)	 100°C 150°C 60~120 sec	 150°C 200°C 60~180 sec
Tsmax to T_L - Ramp-up Rate	 <3°C/sec	 <3°C/sec
Time maintained above: - Temperature (T_L) - Time (t_L)	 183°C 60~150 sec	 217°C 60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec